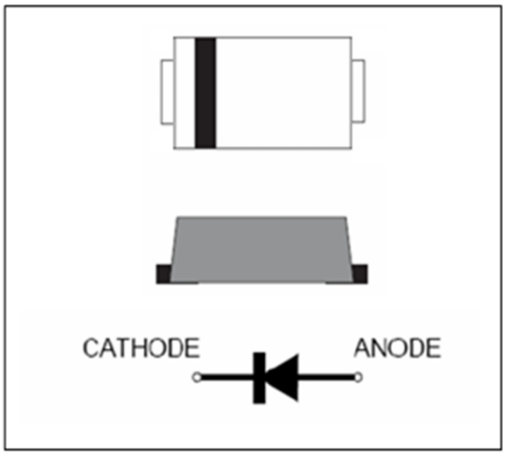
LMBR0520FT1G thru LMBR0540FT1G

Schottky Barrier Rectifiers

Reverse Voltage 20 to 40V Forward Current 0.5A

FEATURES

* Plastic package has Underwriters Laboratory Flammability Classification 94V-0
* Low power loss,high efficiency
* For use in low voltage high frequency inverters, free wheeling,and polarity protection applications
* Guardring for over voltage protection
* High temperature soldering guaranteed: 260°C/10 seconds at terminals



We declare that the material of product is Haloggen free (green epoxy compound)

Mechanical Data

Case: SOD123-FL/MINI SMA molded plastic over sky die
Terminals: Tin Plated, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight: 0.0155 g
Handling precautin:None

1.Electrical Characteristic

Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR0520FT1G	LMBR0530FT1G	LMBR0540FT1G	Unit
device marking code		052	053	054	
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	V
Maximum RMS voltage	V_{RMS}	14	21	28	V
Maximum DC blocking voltage	V_{DC}	20	30	40	V
Maximum average forward rectified current at TA = 75°C	$I_{F(AV)}$	0.5			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30			A
Typical thermal resistance (Note 1)	$R\theta J_A$ $R\theta J_C$	110 40			°C/W
Operating junction temperature range	T_J	–55 to +125		–55 to +150	°C
storage temperature range	T_{STG}	–65 to +175			°C

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR0520FT1G	LMBR130FT1G	LMBR0540FT1G	Unit
Maximum instantaneous forward voltage at(IF = 0.1 A, TJ = 25°C) (IF = 0.5 A, TJ = 25°C)	V_F	0.3 0.385	0.375 0.450	- 0.55	V
Maximum DC reverse current at rated DC blocking voltage TA = 25℃ Tj = 100℃	I_R	0.25 8	0.130 10	0.04 10	mA
Typical junction capacitance at 4.0V, 1MHz	C_J	160			PF

NOTES:

1. 8.0mm^2 (.013mm thick) land areas

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2.Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 – Forward Current Derating Curve

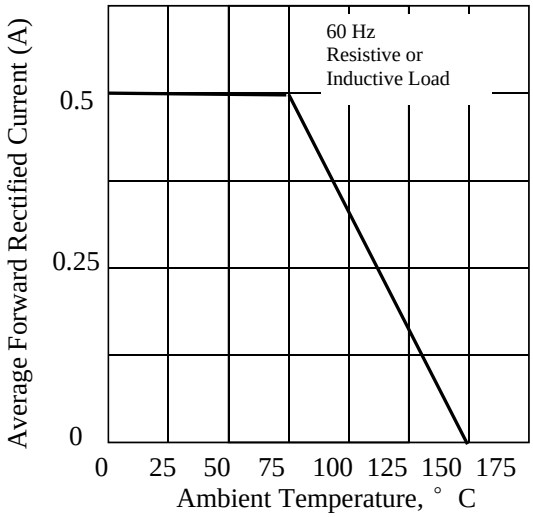


Fig. 2 – Maximum Non-repetitive Peak Forward Surge Current

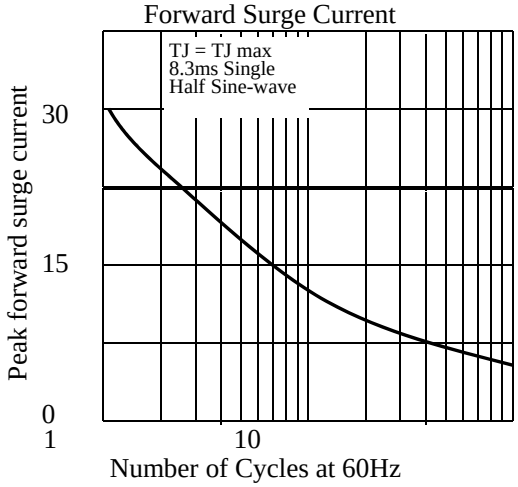


Fig 3. – Typical Instantaneous Forward Characteristics

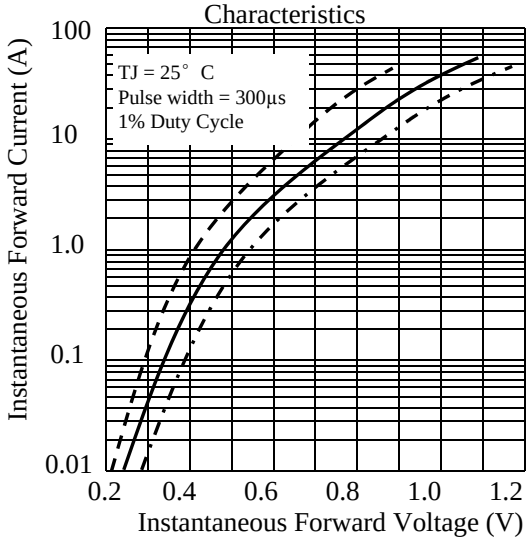


Fig 4. – Typical Reverse Characteristics

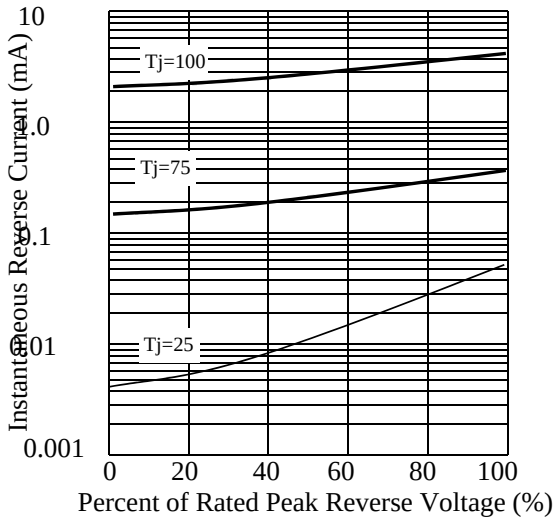


Fig 5. – typical transient thermal impedance

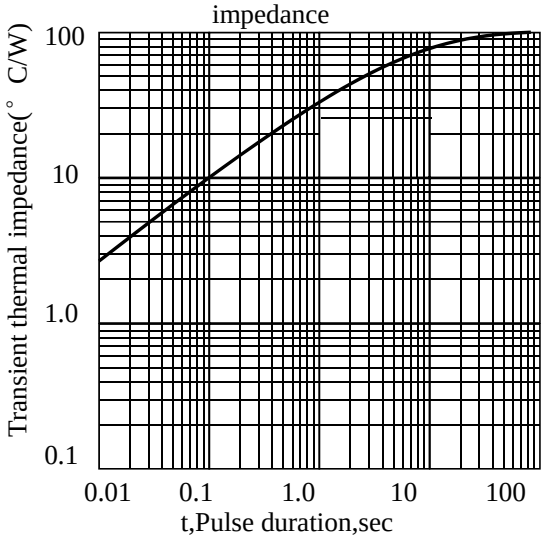
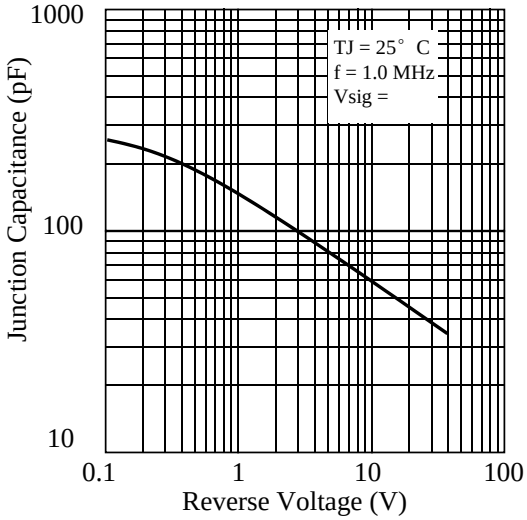


Fig 6. – Typical Junction Capacitance



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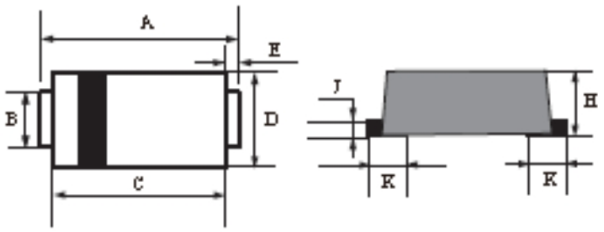
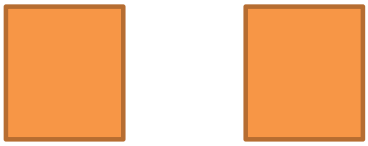
3. dimension:

SOD123-FL



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	3.5	3.9	0.138	0.159
B	0.75	0.95	0.029	0.037
C	2.6	3.0	0.103	0.119
D	1.6	2.0	0.063	0.079
E	0.45Typ		0.018Typ	
H	0.9	1.2	0.036	0.047
J	0.12	0.22	0.005	0.009
K	0.8Typ		0.032Typ	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD123-FL	0.044(1.10	0.040(1.00)	0.079(2.00)

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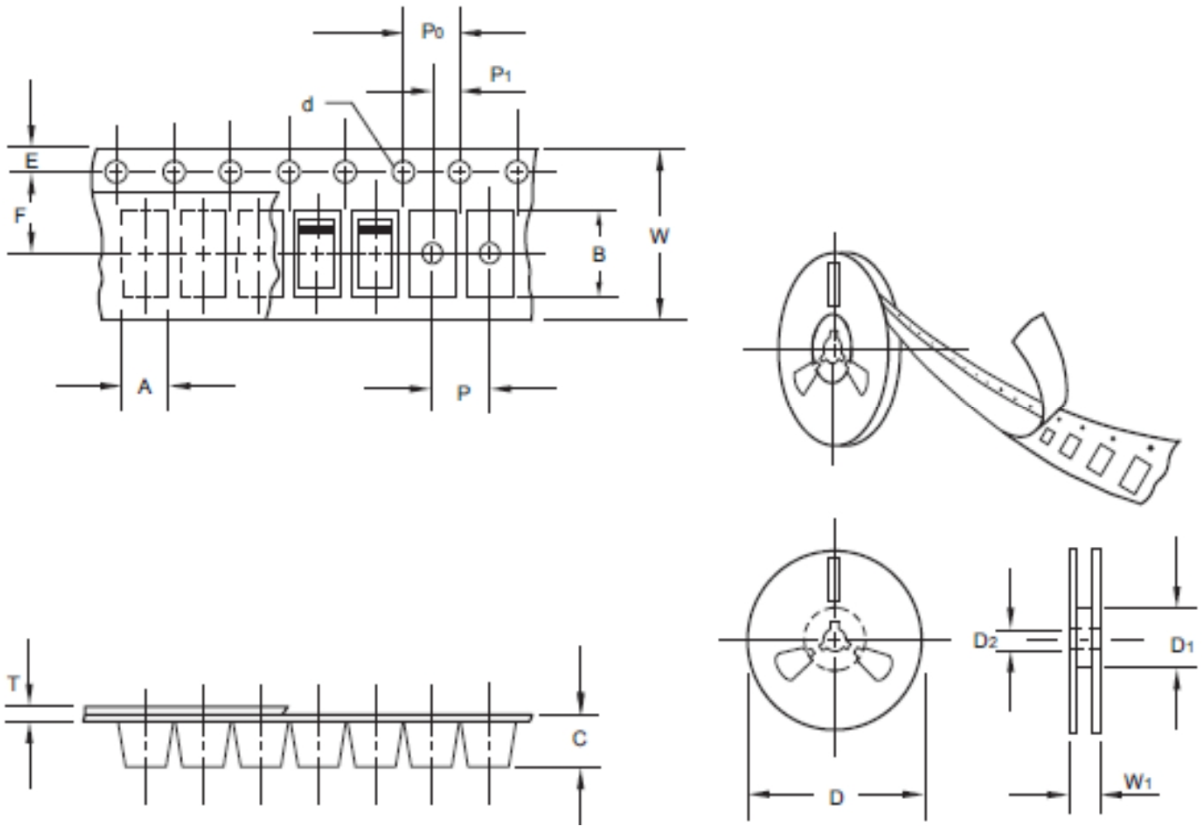
4.Packing information



Unit：mm

Item	Symbol	tolerance	SOD123-FL
Carrier width	A	0.1	2.00
Carrier length	B	0.1	3.85
Carrier depth	C	0.1	1.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D_1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D_1	min	62.00
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Spocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W_1	1.0	11.40

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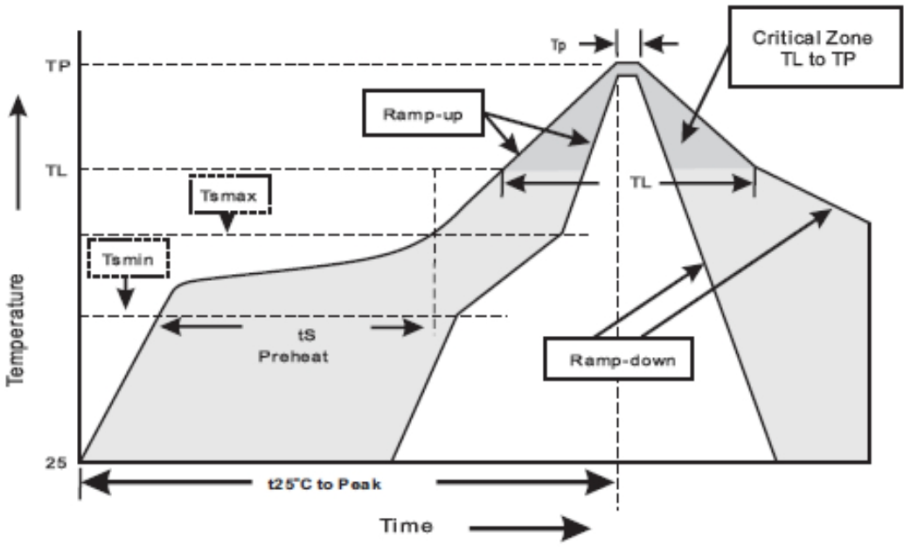
Reel packing

PACKAGE	REEL SIZE	REEL (PCS)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA. (mm)	CARTON SIZE (mm)	CARTON (PCS)	APPOX. GROSS WEIGHT (kg)
SOD123-FL	7"	3,000	4.0	30,000	183*183*123	178	382*262*387	240,000	8.7

5.Suggested thermal profile for soldering process

1. Storage environment：Temperature=5~40℃ Humidity=55±25%
2. Reflow soldering of surface-mount device



3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3℃/sec
Preheat - Temperature Min(Tsmin) - Temperature Max(Tsmax) - Time(min to max)(t_S)	 150℃ 200℃ 60~120sec
Tsmax to T_L - Ramp-up Rate	 <3sec
Time maintained above: - Temperature (T_L) - Time(t_L)	 217℃ 60-260sec
Peak Temperature(T_P)	255 -0/+5℃
Time within 5℃ of actual Peak Temperature(T_P)	10~30sec
Ramp-down Rate	<6℃/sec
Time 25℃ to Peak Temperature	<6minutes

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6.High reliability test capabilities

Item Test	Condition	Reference
Solder Resistance	at 260±5℃ for 10±2sec immerse body into solder 1/16" ± 1/32"	MIL-STD-750D METHOD-2031
Solderability	at 245±5℃ for 5 sec	MIL-STD-202F METHOD-208
High Temperature Reverse Bias	V_R=80% rate at T_j=150℃ for 168hrs	MIL-STD-750D METHOD-1038
Forward Operation Life	Rated average rectifier current T_A=25℃ for 500hrs	MIL-STD-750D METHOD-1027
Intermittent Operation Life	T_A=25℃，I_F=I_O On state:power on for 5 min. Off state:power off for 5 min. on and off for 500 cycles	MIL-STD-750D METHOD-1036
Pressure Cooker	15P_{SIG} at T_A=121℃ for 4hrs	JESD22-A102
Temperature Cycling	-55℃ to +125℃ dwelled for 30 min. and transferred for 5min. Total 10 cycles	MIL-STD-750D METHOD-1051
Thermal Shock	0℃ for 5min. Rise to 100℃ for 5min. Total 10 cycles	MIL-STD-750D METHOD-1056
Forward Surge	8.3ms single half sine-wave superimposed on rated load,one surge	MIL-STD-750D METHOD-4066-2
Humidity	at T_A=85℃，R_H=85% for 1000hrs	MIL-STD-750D METHOD-1021
High Temperature Storage Life	at 175℃ for 1000hrs	MIL-STD-750D METHOD-1031

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7. Update Record

版次	更新记录	更新作者	更新日期
1	第一版	周杰	2013.04.03